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Prodn. of copper-coated polyimide substrate - by etching surface of polyimide resin film, surface-treating with alkali soln., applying catalyst, activating, electroless plating, heat-treating, and forming C95-141368	<u>ADVANTAGE</u> Polyimide resin film has high adhesion strength even with thick polyimide resin film. (4pp003DwgNo.0/0)(NA) (4ppDwgNo.0/0)

The prodn. of Cu-coated polyimide substrates comprises subjecting the surface of the polyimide resin film to etching, and then surface-treating with an alkali soln. of concn. 0.1-5 mol/l at 0-50° C; applying a catalyst for electroless plating; activating the applied catalyst; electroless-plating one of Ni, Co or other metal alloy; heat-treating the obtd. plated material in an inert atmos.; and forming electro-Cu plating on the electroless plating layer. Na hydroxide soln. or K hydroxide soln. is used as the alkali soln..

USE
Used to produce Cu-coated polyimide substrates for printed-wiring boards (PWB), e.g., flexible printed circuit (FPC) or tape-automatic bonding (TAB) tape.

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